

Retrouver les citations sur Questel•Orbit

Depuis le XX juillet 2002, Questel•Orbit vous propose deux nouvelles commandes, CITF et CITB, qui vous permettent de retrouver facilement les brevets cités et citants dans six bases de données Brevets.

Une troisième commande, FAMCITE, est également disponible dans la base PlusPat et vous permet d'afficher automatiquement une revue de citations complète.

■ Les commandes CITF et CITB : la recherche automatique de citations

Ces deux commandes sont disponibles dans les six bases de données suivantes :

- EPPATENT, les brevets européens
- FRPATENT, les brevets français
- WOPATENT, les demandes PCT
- USPAT, les brevets américains
- DEPAT, les brevets et modèles d'utilité allemands
- PLUSPAT, l'offre mondiale des brevets

CITF permet de retrouver l'information sur les brevets citants. Suite à une étape de recherche, la commande va extraire tous les numéros de publication obtenus dans le lot de réponses et les rechercher en tant que brevets cités.

Exemple de syntaxe : CITF QU 1

CITB permet de retrouver l'information sur les brevets cités. Suite à une étape de recherche, la commande va extraire tous les numéros de brevets cités obtenus dans le lot de réponses et les rechercher en tant que numéros de publication.

Exemple de syntaxe : CITB QU 3

Dans les deux cas, les numéros de publication du lot de départ seront intégrés dans le résultat final.

Vous pouvez utiliser ces commandes en recherche multi-bases en entrant le paramètre DEPUIS suivi du nom de l'une des bases de données du cluster.

Exemple de syntaxe : CITF QU 1 DEPUIS EPPATENT

Tarif : Questel•Orbit n'applique pas de surcoût pour l'utilisation des commande CITF et CITB. Seuls le temps de connexion puis la visualisation des documents sont facturés au tarif de la base utilisée.

Exemple d'utilisation

Base selectionnee: FRPATENT

Question 1

cheron/in et pile a combustible

** Question 1, nombre de reponses 12

Question 2

citf qu 1

** Question 2, nombre de reponses 15

Question 3

vi cite 1-2

1/15 FRPATENT - (C) Questel.Orbit- image
CPIM

PUB - FR2535903 - 19840511 [FR2535903]

RR - Rapport de Recherche

- US3554810(A) (Cat. A); US3513031(A) (Cat. A); FR1571100(A) (Cat. A)

; FR2287783(A) (Cat. A); DE43394(C) (Cat. A); US4198475(A) (Cat. A)

; DE2131394(A) (Cat. A); DE2621081(A) (Cat. A); US3758342(A) (Cat. A)

BRR - 1986-51

DRR - 1986-12-19

2/15 FRPATENT - (C) Questel.Orbit- image
CPIM

PUB - FR2499774 - 19820813 [FR2499774]

RR - Rapport de Recherche

- FR1323173(A); FR2347786(A); US3554803(A)

BRR - 1982-32

DRR - 1982-08-13

Question 3

citb qu 1

** Question 3, nombre de reponses 16

Question 4

vi cite 1-2

1/16 FRPATENT - (C) Questel.Orbit- image
CPIM

PUB - FR2499774 - 19820813 [FR2499774]

RR - Rapport de Recherche

- FR1323173(A); FR2347786(A); US3554803(A)

BRR - 1982-32

DRR - 1982-08-13

2/16 FRPATENT - (C) Questel.Orbit- image
CPIM

PUB - FR2442517 - 19800620 [FR2442517]

RR - Rapport de Recherche

- FR1486405(A); US3589941(A); US3268364(A); US1359881(A)

BRR - 1980-25

DRR - 1980-06-20

■ La commande FAMCITE : l'affichage automatique d'une revue de citations

L'utilisation de la commande FAMCITE est réservée à la base PlusPat. Elle permet, après l'exécution d'une recherche famille sur un numéro de brevet, de visualiser une revue de citations complète.

Cette revue de citations est structurée en trois parties :

- La famille du brevet
- Les citants : Brevets citant un membre de cette famille
- Les cités : Brevets cités par un membre de cette famille

En ce qui concerne les documents citants et cités, une recherche famille est automatiquement réalisée, ce qui permet d'afficher l'ensemble des résultats sous la forme de une famille par référence.

Le format de visualisation implicitement associé à la commande FAMCITE est le format MCIT qui contient les champs suivants :

- PN Numéro et date de publication de tous les membres
- TI Titre anglais du premier membre
- OTI Titre en langue non anglaise du premier membre
- PA Déposant du premier membre
- IN Inventeur(s) du premier membre
- AP Numéro de dépôt de tous les membres
- PR Numéro de priorité de tous les membres
- CT Citations des membres EP, WO, US et FR
- AB Abrégé du premier membre

Il est également possible de demander la visualisation du dessin en ajoutant le paramètre IMG. La syntaxe sera donc **FAMCITE IMG**. L'utilisation des options de visualisation de type LEGAL et FULLTEXT n'est pas autorisée avec la commande FAMCITE.

Tarif : La commande FAMCITE est facturée au tarif forfaitaire de 16 euros HT quel que soit le nombre de documents visualisés (images des dessins en sus).

Exemple d'utilisation

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Question 1
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fam ep326539/pn
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1 groupes brevets
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** Question 1, nombre de reponses 4
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Question 2
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famcite
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<< Revue de citations >>
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<< La famille du brevet >>
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1/1 PLUSPAT - (C) QUESTEL-ORBIT- image
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CPIM (C) Questel-Orbit
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PN - EP0326539 A1 19890802 [EP-326539]  
AU2886889 A 19890803 [AU8928868]  
AU608943 B2 19910418 [AU-608943]  
JP2006048 A 19900110 [JP02006048]  
JP3029501 B 19910424 [JP91029501]  
JP1663220 C 19920519 [JP1663220]  
US4871109 A 19891003 [US4871109]
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- TI - (A1) Vapor phase soldering using certain perfluorinated polyethers.
OTI - (A1) Soudage en phase vapeur utilisant certains polyethers perfluores.
- (A1) Dampfphasen-Lotung unter Verwendung bestimmter perfluorierter Polyether.
- PA - (A1) MONSANTO CO (US)
IN - (A1) FISHER DAVID OSCAR; MCCONAGHY JOHN STEAD JR; KALOTA DENNIS JEROME; ZIELINSKI RONALD EDWARD
AP - 1989EP-0870018; 1989AU-0028868; 1988US-0149773; 1989JP-0019416
PR - 1988US-0149773
CT - (EP-326539)
Cited in the search report
- DE3223471 (A); DE3715940 (A); US3866307 (A)
- CT - (US4871109)
USRe30399; US2500388; US3866307; US3904102; US3947240
- AB - (EP-326539)
A perfluorinated polyether having the formula $R_fO-(CF_2CF_2O)_n-R$ min f wherein $n=3-11$ and R_f and R_f min are perfluorinated C1-C5 alkyl radicals is used in vapor phase soldering applications. Especially useful for such applications is perfluoroheptaglyme.

<< Les citants: Brevets citant un membre de cette famille >>

- 1/5 PLUSPAT - (C) QUESTEL-ORBIT- image
CPIM (C) Questel-Orbit
PN - FR2795596 A1 20001229 [FR2795596]
TI - (A1) Electrical installation electrical/electronic component printed circuit board soldering having soldering unit with printed circuits and liquid heat carrier following specific temperature pre heat/refusion cycle
- OTI - (A1) PROCEDE ET INSTALLATION DE SOUDURE DE COMPOSANTS SUR UN SUPPORT, TELS QUE NOTAMMENT DES COMPOSANTS ELECTRIQUES ET/OU ELECTRONIQUES SUR UN CIRCUIT IMPRIME
- PA - (A1) S N V (FR)
IN - (A1) VAL BERNARD; THOMAS DEREK J
AP - 1999FR-0008338
PR - 1999FR-0008338
CT - (FR2795596)
Cited in the search report
- US4840305 (A) (Cat. X); EP326539 (A) (Cat. A); EP182036 (A) (Cat. A)

- 2/5 PLUSPAT - (C) QUESTEL-ORBIT- image
CPIM (C) Questel-Orbit
PN - US5188282 A 19930223 [US5188282]
TI - (A) Vapor phase flash fusing of printed wiring boards
PA - (A) HUGHES AIRCRAFT CO (US)
IN - (A) JOHNSON KIRK E (US); MODZELEWSKI EDWARD (US)
AP - 1991US-0646589
PR - 1991US-0646589
CT - (US5188282)
US4022371; US4392049; US4552300; US4767471; US4838476; US4840305; US4871109; US4874124; US4898991; US4919729
- AB - (US5188282)
An improved process for the fusing a tin-lead solder mixture deposited to form a finished circuit on a printed circuit or wiring board. The method comprises the rapid or flash fusing of the circuit board having the tin-lead solder mixture deposited thereon by immersing into the vapor of an inert fluid having a boiling point just above the melting point of the solder alloy. Problems with "weak knee" conditions are avoided by adjusting the heating time-at-temperature to that which allows the desired tin-lead solder alloy to form only as a thick "mush" rather than as a molten fluid. By so doing, the solder alloy is formed without the necessary degree of fluidity that causes it to draw away from the edge or rim of plated holes in the board.

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3/5 PLUSPAT - (C) QUESTEL-ORBIT- image

CPIM (C) Questel-Orbit

PN - US4996369 A 19910226 [US4996369]

US5076949 A 19911231 [US5076949]

US5120459 A 19920609 [US5120459]

TI - (A) Novel perfluorinated polyethers and process for their preparation

PA - (A) MONSANTO CO (US)

IN - (A) KALOTA DENNIS J (US); MCCONAGHY JR JOHN S (US); FOERST PAUL W (US); LIU PAUL H (US); FEHER JR FRANK R (US)

AP - 1990US-0498124; 1990US-0498055; 1990US-0498057

PR - 1989US-0150963; 1990US-0498055; 1990US-0498057; 1990US-0498124

CT - (US5076949)

US3505229; US3801505; US3909431; US4523039; US4803005; US4808323;

US4871109; US4900463; US4925583; EP269029; EP332601

CT - (US5120459)

US3505229; US3801505; US3909431; US4523039; US4803005; US4808323;

US4900463; EP269029

CT - (US4996369)

US4523039

AB - (US5076949)

Perfluorinated polyethers having the formula $R_fO-(CF_2CF_2O)_n-R'_f$ wherein n is an integer of 1-11 and each of R_f and R'_f is a perfluorinated C1-C5-alkyl radical, dimers of such polyethers and carbon to carbon intramolecularly coupled cyclic derivatives of such polyethers are produced by direct fluorination of the polyethers in an inert solvent. Compositions of the perfluorinated polyethers and their derivatives are useful as functional fluids.

4/5 PLUSPAT - (C) QUESTEL-ORBIT

PN - EP0521462 A2 19930107 [EP-521462]

EP0521462 A3 19930519 [EP-521462]

TI - (A2) Method for smelting thermoplastic polymers.

OTI - (A2) Verfahren zum Schmelzen von Thermoplasten.

- (A2) Procède pour la fusion des polymeres thermoplastiques.

PA - (A2) HOECHST AG (DE)

IN - (A2) NAUMANN JOACHIM (DE); SCHMELZER HEINZ (DE)

AP - 1992EP-0111061

PR - 1991DE-4121802

CT - (EP-521462)

Cited in the search report

- US4940072(A) (Cat. X); EP326539(A) (Cat. A); EP361247(A) (Cat. A)

AB - (EP-521462)

The invention relates to a process for melting thermoplastics by bringing the thermoplastics into contact with the hot vapour of a perfluorinated organic compound, the vapour having at least the temperature necessary to melt the thermoplastic used.

5/5 PLUSPAT - (C) QUESTEL-ORBIT- image

CPIM (C) Questel-Orbit

PN - EP0450329 A2 19911009 [EP-450329]

EP0450329 A3 19930929 [EP-450329]

EP0450329 B1 19970709 [EP-450329]

DE69126725 D1 19970814 [DE69126725]

DE69126725 T2 19980115 [DE69126725]

JP5050220 A 19930302 [JP05050220]

JP2530757 B2 19960904 [JP2530757]

US5102028 A 19920407 [US5102028]

TI - (A2) Localized soldering station.

OTI - (A2) rtlich begrenzte Lotstation.

- (A2) Station a souder localisee.

PA - (A2) IBM (US)

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IN - (A2) LYNCH ROBERT JOHN (US); GLOVATSKY ANDREW ZACHARY (US); MOTTER JAMES GEORGE JR (US); REPCHAK STEVE ANDREW (US); VITTONI JEAN MARIE (US); YETTER LAWRENCE ROBERT (US)

AP - 1991EP-0103346; 1991DE-6026725; 1991US-0725415; 1991JP-0036207

PR - 1990US-0503320; 1991US-0725415

CT - (EP-450329)

Cited in the search report

- EP326539(A) (Cat. A); WO9003103(A) (Cat. A); EP205309(A) (Cat. A); US4762264(A) (Cat. A,D)

- IBM TECHNICAL DISCLOSURE BULLETIN, vol. 13, no. 3, August 1970, NEW YORK, US; (E.G. DINGMAN): 'solvent vapor solder reflow' (Cat. A,D)

CT - (US5102028)

US4270260; US4561586; US4747533; US4762264; US4782991; US4799617; US4828162; JP192260

- "Vapor Phase Solder Reflow for Hybrid Circuit Manufacturing", Spigarelli, Solid State Technology, pp. 50-53, Oct. 1976.

3M Fluorinert Electronic Liquids, Commercial Chemicals Division, 2-1984.

IBM Technical Disclosure Bulletin, "Soldering Tool Employing Hot Vapors", vol. 22, No. 5, pp. 1833-1838, Oct. 1979.

Research Disclosure, "Solder Process Monitor", Kenneth Mason Publications Ltd, England, No. 258, Oct. 1985.

IBM Technical Disclosure Bulletin, ". . . Vapor Phase Soldering Equipment", vol. 30, No. 2, pp. 549-551, Jul. 1987.

IBM Technical Disclosure Bulletin, vol. 13, No. 3, "Solvent Vapor Solder Reflow", Aug. 1970, p. 639; by E. G. Dingman.

AB - (EP-450329)

A localized soldering station (10) is described that uses the vapor phase reflow principle. A container (11) has of a medium selected because of the temperature at which it changes to a vapor. A heated conduit (14) maintains the vapor state while conveying the vapor to a work location (13) where a module (28) with a part to be removed or attached by solder connections is supported. A transparent, quartz nozzle (27) confines the vapor to the part and its solder connections and is positioned accurately by a unit that includes a guide light (29). Vapor will lose its latent heat of vaporization upon contact with the part and its solder connections, causing the solder to reflow and change back to a liquid, which is collected for reuse. When in a standby or ready condition, vapor is conveyed up through a shutoff valve (15) through cooling fins (16) where it changes back to a liquid and returns to the container (11), avoiding loss.

<IMAGE>

<< Les cites: Brevets cites par un membre de cette famille >>

1/6 PLUSPAT - (C) QUESTEL-ORBIT

PN - US2500388 A 19500314 [US2500388]

TI - (A) Fluorocarbon ethers

PA - (A) MINNESOTA MINING & MFG

IN - (A) SIMONS JOSEPH H

AP - 1948US-0039999

PR - 1948US-0039999

2/6 PLUSPAT - (C) QUESTEL-ORBIT- image

CPIM (C) Questel-Orbit

PN - DE3715940 A1 19881201 [DE3715940]

DE3715940 C2 19920910 [DE3715940]

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- TI - (A1) Infrared soldering furnace for reflow soldering of electronic components on printed circuit boards
- OTI - (A1) INFRAROT-LOETOFEN ZUM AUFSCHMELZLOETEN VON ELEKTRONISCHEN BAUELEMENTEN AUF LEITERPLATTEN
- PA - (A1) HIMMELREICH LOTHAR DIPL ING (DE)
- IN - (A1) HIMMELREICH LOTHAR DIPL ING (DE)
- AP - 1987DE-3715940
- PR - 1987DE-3715940
- AB - (DE3715940)

In an infrared soldering furnace for reflow soldering electronic components on printed circuit boards 38 using a solder paste, said printed circuit boards rest on a support (support surface 37) which is transparent to infrared radiation. Infrared radiators 39-42 which heat the assembled printed circuit boards 38 during a heating phase and a melting phase at different temperatures are arranged above and below the support. The printed circuit boards 38 are then cooled. A drawer 27 on whose support surface 37 the assembled printed circuit boards are placed is provided for introducing the assembled printed circuit boards 38 into the infrared soldering furnace. During the heating phase and the melting phase of the solder paste, the drawer is fixed in the housing. The infrared panel radiators 39-42 have a low thermal inertia and are arranged parallel to the support surface 37 at distances large enough to ensure they heat the support surface uniformly. The support or the support surface 37 and the infrared radiators 39-42 are arranged in a forced-draught exhaust-air duct 2 in the infrared soldering furnace. The infrared radiators 39-42 are powered by a time-controlled temperature control device 25 so that the stationary, assembled printed circuit boards are heated with the desired temperature profile.

<IMAGE>

3/6 PLUSPAT - (C) QUESTEL-ORBIT- image

CPIM (C) Questel-Orbit

- PN - US4389797 A 19830628 [US4389797]
CA1182688 A1 19850219 [CA1182688]
DE3223471 A1 19830120 [DE3223471]
FR2507918 A1 19821224 [FR2507918]
FR2507918 B1 19871113 [FR2507918]
GB2105208 A 19830323 [GB2105208]
GB2105208 B 19850925 [GB2105208]
JP58006774 A 19830114 [JP58006774]
- TI - (A) Continuous vapor processing system
- OTI - (A1) APPAREIL DE TRAITEMENT CONTINU A LA VAPEUR, PAR EXEMPLE POUR SOUDER OU DEGRAISSER DES PIECES A LA VAPEUR
- PA - (A) HTC CORP
- IN - (A) SPIGARELLI DONALD J; DUSTIN PAUL C
- AP - 1982DE-3223471; 1981US-0276493; 1982CA-0405662; 1982GB-0018202; 1982FR-0011005; 1982JP-0108241
- PR - 1981US-0276493
- CT - (US4389797)
US3000346; US3408748; US3904102; US3996949; US4277518
- CT - (FR2507918)
Search report
- FR3996949(A) (Cat. Y);FR2243045(A) (Cat. Y);FR3996949(A) (Cat. X);EP0023107(A) (Cat. A);GB2063925(A) (Cat. A)
- AB - (US4389797)

A continuous vapor processing system for vapor phase soldering, degreasing, or similar processes wherein a product is moved into and out of a vessel in a continuous manner via open conduits or channels while preventing escape of vapor from the processing tank and the conduits.

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4/6 PLUSPAT - (C) QUESTEL-ORBIT- image

CPIM (C) Questel-Orbit

PN - US3947240 A 19760330 [US3947240]

TI - (A) METHOD AND APPARATUS FOR GENERATING A VAPOR FOR SOLDERING FUSING
OR BRAZING ARTICLES

PA - (A) WESTERN ELECTRIC CO

IN - (A) PFAHL JR ROBERT C

AP - 1974US-0520182

PR - 1974US-0520182

CT - (US3947240)

US2153942; US3710450; US3732063

AB - (US3947240)

A heat transfer liquid having a boiling point at atmospheric pressure at least equal to the temperature at which a soldering, fusing or brazing operation is to be performed, is floated on a pool of a liquifiable metal having a density greater than, a melting point below, and a heat of vaporization above, that of the liquid. The metal is heated to a temperature between its melting and boiling points, and at least to the boiling point of the liquid, to continuously boil the liquid to establish a body of hot, saturated vapor having a density greater than that of air at atmospheric pressure. An article on which the soldering, fusing or brazing operation is to be performed is extended into the body of vapor to condense the vapor thereon. The latent heat of vaporization of the condensing vapor heats the article to the temperature for the operation, and the article is then withdrawn from the vapor for cooling.

5/6 PLUSPAT - (C) QUESTEL-ORBIT- image

CPIM (C) Questel-Orbit

PN - US3866307 A 19750218 [US3866307]

AU7293274 A 19760311 [AU7472932]

BE819569 A1 19741231 [BE-819569]

BR7407403 D0 19750909 [BR7407403]

CA1018831 A1 19771011 [CA1018831]

CA1019644 A1 19771025 [CA1019644]

CH602251 A5 19780731 [CH-602251]

DE2442180 A1 19750313 [DE2442180]

DE2442180 B2 19790426 [DE2442180]

DE2442180 C3 19791220 [DE2442180]

ES449417 A1 19771101 [ES-449417]

FR2243045 A1 19750404 [FR2243045]

FR2243045 B1 19790803 [FR2243045]

GB1484604 A 19770901 [GB1484604]

IT1020737 B 19771230 [IT1020737]

JP50054552 A 19750514 [JP50054552]

JP53040934 B 19781030 [JP78040934]

JP964126 C 19790720 [JP-964126]

JP53112243 A 19780930 [JP53112243]

JP54014066 B 19790604 [JP79014066]

JP981487 C 19791227 [JP-981487]

NL7411686 A 19750311 [NL7411686]

NL163732 C 19801015 [NL-163732]

SE7410907 A 19750310 [SE7410907]

SE424518 B 19820726 [SE-424518]

SE424518 C 19821104 [SE-424518]

US3904102 A 19750909 [US3904102]

TI - (A) APPARATUS AND METHOD FOR SOLDERING, FUSING OR BRAZING

OTI - (A1) VORRICHTUNG UND VERFAHREN ZUM LOETEN, SCHMELZEN ODER HARTLOETEN

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PA - (A) WESTERN ELECTRIC CO
IN - (A) MOLLENDORF JOSEPH CHARLES; PFAHL JR ROBERT CHRISTIAN; CHU TZE YAO
AP - 1974US-0476343; 1976ES-0449417; 1974NL-0011686; 1974IT-0069710;
1974SE-0010907; 1974CH-0012063; 1974AU-0072932; 1974DE-2442180;
1974BR-0007403; 1974CA-0207881; 1974GB-0038584; 1974FR-0030363;
1977JP-0154583; 1974JP-0102535; 1973US-0395310; 1974BE-0148225;
1974CA-0207772

PR - 1973US-0395310; 1974US-0476343

CT - (US3904102)
US2123439; US3011924; US3308839; US3375177; US3494793; US3603329;
US3720072; US3728866; US3866307

CT - (US3866307)
US2723448; US2842841; US2844867; US3080648; US3263325; US3409978

AB - (US3904102)

A primary liquid having a boiling point at atmospheric pressure at least equal to the temperature at which a soldering, fusing or brazing operation is to be performed is continuously boiled to establish a body of hot saturated primary vapor having a density greater than that of air at atmospheric pressure. A blanket of secondary vapor, having a density intermediate that of the primary vapor and the atmosphere, is floated on the body of primary vapor to reduce losses thereof to the atmosphere. The article on which the soldering, fusing or brazing operation is to be performed is passed through the body of secondary vapor into the body of primary vapor in the vessel. Primary vapor condenses on the article, the latent heat of vaporization of the condensing primary vapor heating the article to the temperature required for the soldering, fusing or brazing operation. After completion of the operation, the article is withdrawn from the body of primary vapor through the blanketing body of secondary vapor, out of the vessel and into the atmosphere where it is cooled to ambient temperature.

6/6 PLUSPAT - (C) QUESTEL-ORBIT

PN - USRE30399 E 19800909 [USRE30399]
TI - (E) Method for soldering, fusing or brazing

AP - 1977US-0826104

PR - 1977US-0826104

CT - (USRE30399)
US2723448; US2842841; US2844867; US3080648; US3263325; US3375177;
US3409978; US3482755; US3656492; US3686746; US3825164; US3977075
- Dingman "Solvent Vapor Solder Reflow", IBM Tech. Disclosure Bulletin,
v. 13, No. 3, 8-1970, p. 639.

AB - (USRE30399)

. .Article.. An article to be soldered, fused or brazed is placed in hot saturated vapors generated by continuously boiling a heat transfer liquid having selected properties including a boiling point at least equal to, and preferably above, the temperature required for such operation. Vapors condense on the article and give up latent heat of vaporization to heat the article to the temperature for soldering, fusing or brazing. . .Heat.. The heat transfer liquid may be a fluorocarbon. Apparatus is shown for soldering, fusing or brazing a single article, a batch of articles, or a continuously moving line of articles. Specifically, mass reflow soldering and mass wave soldering operations are described.